



## Insulated Gate Bipolar Transistor (Trench IGBT), 175 A




SOT-227

PRODUCT SUMMARY	
$V_{CES}$	1200 V
$I_{C(DC)}$	175 A at 90 °C <sup>(1)</sup>
$V_{CE(on)}$ typical at 100 A, 25 °C	1.73 V
$I_{F(DC)}$	32 A at 90 °C
Speed	8 kHz to 30 kHz
Package	SOT-227
Circuit	Single switch diode

**Note**

<sup>(1)</sup> Maximum collector current admitted is 100 A, to not exceed the maximum temperature of terminals

**FEATURES**

- Trench IGBT technology with positive temperature coefficient
- Square RBSOA
- 10  $\mu$ s short circuit capability
- HEXFRED® antiparallel diodes with ultrasoft reverse recovery
- $T_J$  maximum = 150 °C
- Fully isolated package
- Very low internal inductance ( $\leq 5$  nH typical)
- Industry standard outline
- UL approved file E78996 
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT

**BENEFITS**

- Designed for increased operating efficiency in power conversion: UPS, SMPS, welding, induction heating
- Easy to assemble and parallel
- Direct mounting to heatsink
- Plug-in compatible with other SOT-227 packages
- Very low  $V_{CE(on)}$
- Low EMI, requires less snubbing

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	$V_{CES}$		1200	V
Continuous collector current	$I_C$ <sup>(1)</sup>	$T_C = 25$ °C	288	A
		$T_C = 90$ °C	175	
Pulsed collector current	$I_{CM}$		450	
Clamped inductive load current	$I_{LM}$		450	
Diode continuous forward current	$I_F$	$T_C = 25$ °C	54	
		$T_C = 90$ °C	32	
Gate to emitter voltage	$V_{GE}$		$\pm 20$	V
Power dissipation, IGBT	$P_D$	$T_C = 25$ °C	1087	W
		$T_C = 90$ °C	522	
Power dissipation, diode	$P_D$	$T_C = 25$ °C	219	
		$T_C = 90$ °C	105	
Isolation voltage	$V_{ISOL}$	Any terminal to case, $t = 1$ min	2500	V

**Note**

<sup>(1)</sup> Maximum collector current admitted is 100 A, to do not exceed the maximum temperature of terminals



ELECTRICAL SPECIFICATIONS (T <sub>J</sub> = 25 °C unless otherwise specified)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Collector to emitter breakdown voltage	V <sub>BR(CES)</sub>	V <sub>GE</sub> = 0 V, I <sub>C</sub> = 250 μA	1200	-	-	V	
Collector to emitter voltage	V <sub>CE(on)</sub>	V <sub>GE</sub> = 15 V, I <sub>C</sub> = 100 A	-	1.73	2.1		
		V <sub>GE</sub> = 15 V, I <sub>C</sub> = 100 A, T <sub>J</sub> = 125 °C	-	1.98	2.2		
		V <sub>GE</sub> = 15 V, I <sub>C</sub> = 100 A, T <sub>J</sub> = 150 °C	-	2.05	-		
Gate threshold voltage	V <sub>GE(th)</sub>	V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 250 μA	-	5	-		
		V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 7.5 mA	4.9	5.9	7.9		
		V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 250 μA, T <sub>J</sub> = 125 °C	-	2.9	-		
Temperature coefficient of threshold voltage	ΔV <sub>GE(th)</sub> /ΔT <sub>J</sub>	V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 1 mA (25 °C to 125 °C)	-	-17.6	-		mV/°C
Collector to emitter leakage current	I <sub>CES</sub>	V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 1200 V	-	0.9	100		μA
		V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 1200 V, T <sub>J</sub> = 125 °C	-	0.85	10		mA
		V <sub>GE</sub> = 0 V, V <sub>CE</sub> = 1200 V, T <sub>J</sub> = 150 °C	-	4	20		
Forward voltage drop, diode	V <sub>FM</sub>	I <sub>F</sub> = 40 A, V <sub>GE</sub> = 0 V	-	3.12	3.44	V	
		I <sub>F</sub> = 40 A, V <sub>GE</sub> = 0 V, T <sub>J</sub> = 125 °C	-	3.15	3.47		
		I <sub>F</sub> = 40 A, V <sub>GE</sub> = 0 V, T <sub>J</sub> = 150 °C	-	3.25	-		
Gate to emitter leakage current	I <sub>GES</sub>	V <sub>GE</sub> = ± 20 V	-	-	± 200	nA	

SWITCHING CHARACTERISTICS (T <sub>J</sub> = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Total gate charge (turn-on)	Q <sub>g</sub>	I <sub>C</sub> = 150 A (t <sub>p</sub> < 400 μs, D < 2 %), V <sub>CC</sub> = 600 V, V <sub>GE</sub> = 15 V	-	830	-	nC		
Gate to emitter charge (turn-on)	Q <sub>ge</sub>		-	180	-			
Gate to collector charge (turn-on)	Q <sub>gc</sub>		-	380	-			
Turn-on switching loss	E <sub>on</sub>	I <sub>C</sub> = 100 A, V <sub>CC</sub> = 720 V, V <sub>GE</sub> = 15 V, R <sub>g</sub> = 2.2 Ω, L = 500 μH, T <sub>J</sub> = 25 °C	-	4.8	-	mJ		
Turn-off switching loss	E <sub>off</sub>		-	7.0	-			
Total switching loss	E <sub>tot</sub>		-	11.8	-			
Turn-on delay time	t <sub>d(on)</sub>		I <sub>C</sub> = 100 A, V <sub>CC</sub> = 720 V, V <sub>GE</sub> = 15 V, R <sub>g</sub> = 2.2 Ω, L = 500 μH, T <sub>J</sub> = 125 °C	-	274	-	ns	
Rise time	t <sub>r</sub>			-	67	-		
Turn-off delay time	t <sub>d(off)</sub>			-	271	-		
Fall time	t <sub>f</sub>			I <sub>C</sub> = 100 A, V <sub>CC</sub> = 720 V, V <sub>GE</sub> = 15 V, R <sub>g</sub> = 2.2 Ω, L = 500 μH, T <sub>J</sub> = 125 °C	-	177	-	mJ
Turn-on switching loss	E <sub>on</sub>				-	6.0	-	
Turn-off switching loss	E <sub>off</sub>				-	10.4	-	
Total switching loss	E <sub>tot</sub>				I <sub>C</sub> = 100 A, V <sub>CC</sub> = 720 V, V <sub>GE</sub> = 15 V, R <sub>g</sub> = 2.2 Ω, L = 500 μH, T <sub>J</sub> = 125 °C	-	16.4	-
Turn-on delay time	t <sub>d(on)</sub>	-				285	-	
Rise time	t <sub>r</sub>	-				75	-	
Turn-off delay time	t <sub>d(off)</sub>	-				306	-	
Fall time	t <sub>f</sub>	-	244			-		
Reverse bias safe operating area	RBSOA	T <sub>J</sub> = 150 °C, I <sub>C</sub> = 450 A, R <sub>g</sub> = 4.7 Ω, V <sub>GE</sub> = 15 V to 0 V, V <sub>CC</sub> = 600 V, V <sub>P</sub> = 1200 V, L = 500 μH	Fullsquare					
Diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 50 A, dI <sub>F</sub> /dt = 200 A/μs, V <sub>R</sub> = 400 V	-			164	-	ns
Diode peak reverse current	I <sub>rr</sub>		-	12		-	A	
Diode recovery charge	Q <sub>rr</sub>		-	994		-	nC	
Diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 50 A, dI <sub>F</sub> /dt = 200 A/μs, V <sub>R</sub> = 400 V, T <sub>J</sub> = 125 °C	-	230		-	ns	
Diode peak reverse current	I <sub>rr</sub>		-	16.5	-	A		
Diode recovery charge	Q <sub>rr</sub>		-	1864	-	nC		
Short circuit safe operating area	SCSOA	T <sub>J</sub> = 150 °C, R <sub>g</sub> = 22 Ω, V <sub>GE</sub> = 15 V to 0 V, V <sub>CC</sub> = 900 V, V <sub>P</sub> = 1200 V	10			μs		



THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Junction and storage temperature range	$T_J, T_{Stg}$		-40	-	150	°C
Junction to case	IGBT					°C/W
	Diode					
Case to heatsink	$R_{thJC}$	Flat, greased surface	-	0.05	-	
Weight			-	30	-	g
Mounting torque		Torque to terminal	-	-	1.1 (9.7)	Nm (lbf.in)
		Torque to heatsink	-	-	1.3 (11.5)	Nm (lbf.in)
Case style		SOT-227				

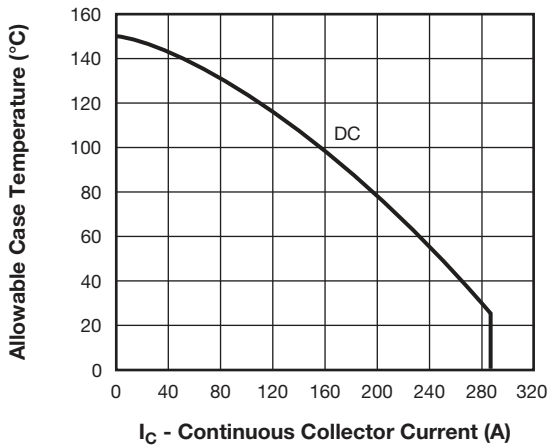


Fig. 1 - Maximum DC IGBT Collector Current vs. Case Temperature

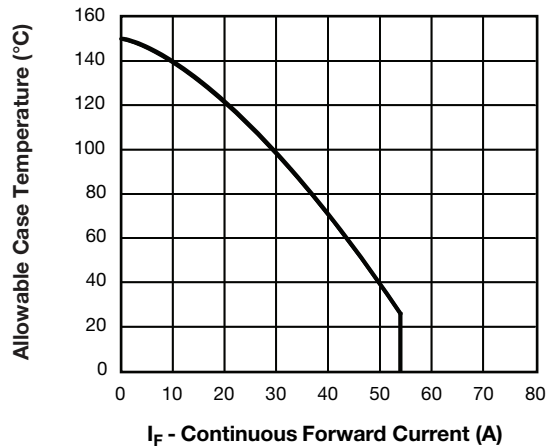


Fig. 3 - Maximum Allowable Forward Current vs. Case Temperature Diode Leg

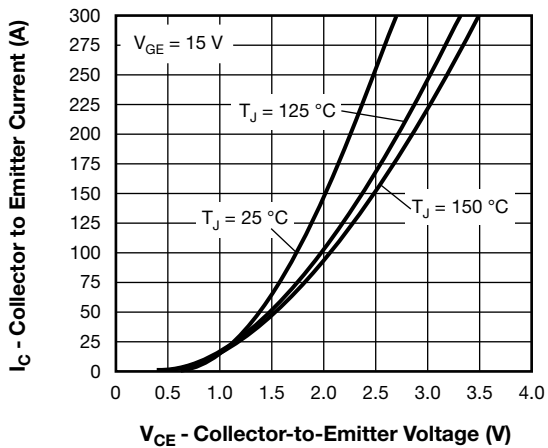


Fig. 2 - Typical Collector to Emitter Current Output Characteristics of IGBT

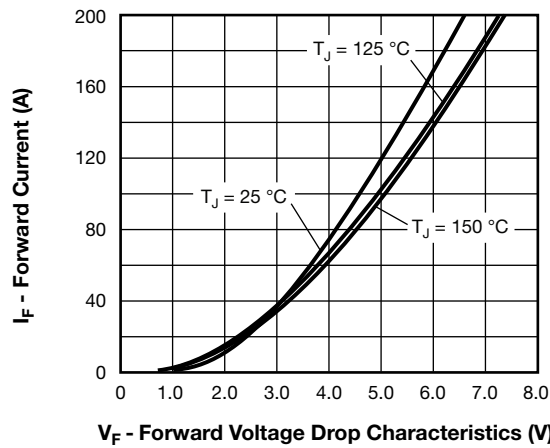


Fig. 4 - Typical Diode Forward Voltage Drop Characteristics

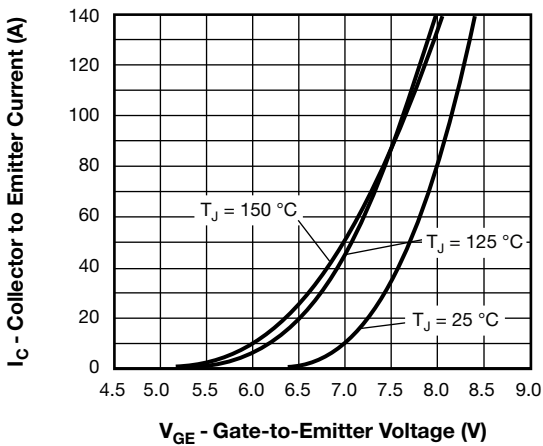


Fig. 5 - Typical IGBT Transfer Characteristics

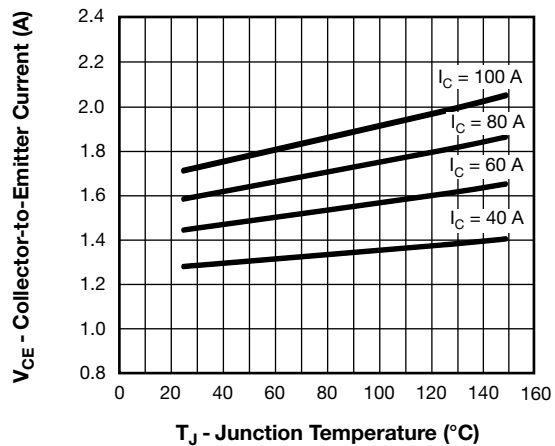


Fig. 8 - Typical IGBT Collector to Emitter Voltage vs. Junction Temperature,  $V_{GE} = 15\text{ V}$

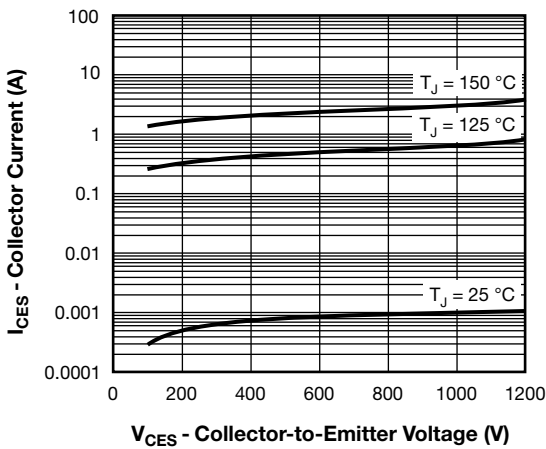


Fig. 6 - Typical IGBT Zero Gate Voltage Collector Current

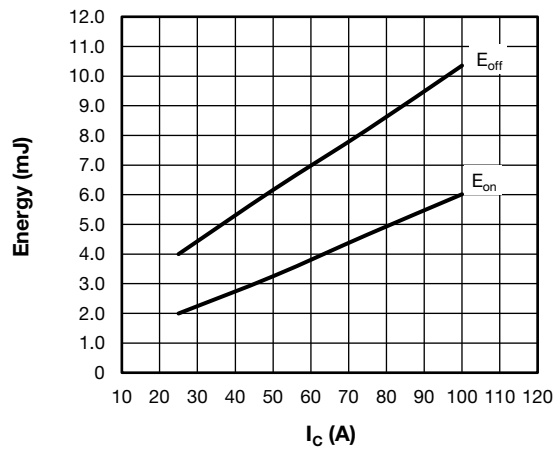


Fig. 9 - Typical IGBT Energy Losses vs.  $I_C$   
 $T_J = 125\text{ °C}$ ,  $L = 500\text{ }\mu\text{H}$ ,  $V_{CC} = 720\text{ V}$ ,  $R_g = 2.2\text{ }\Omega$ ,  $V_{GE} = 15\text{ V}$   
 Diode used: HFA16PB120

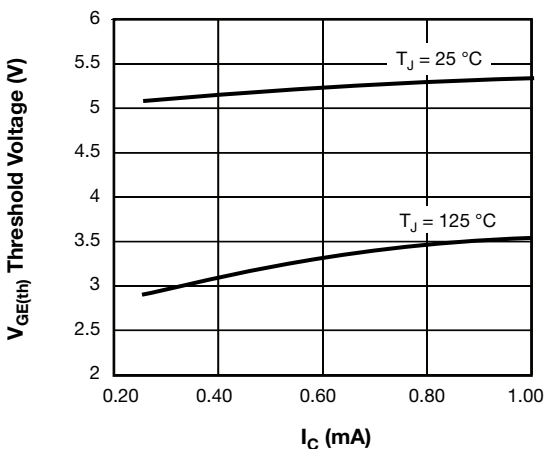


Fig. 7 - Typical IGBT Threshold Voltage

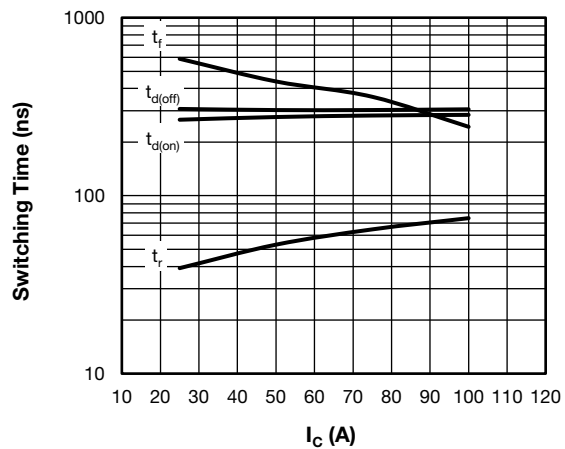


Fig. 10 - Typical IGBT Switching Time vs.  $I_C$   
 $T_J = 125\text{ °C}$ ,  $L = 500\text{ }\mu\text{H}$ ,  $V_{CC} = 720\text{ V}$ ,  $R_g = 2.2\text{ }\Omega$ ,  $V_{GE} = 15\text{ V}$   
 Diode used: HFA16PB120

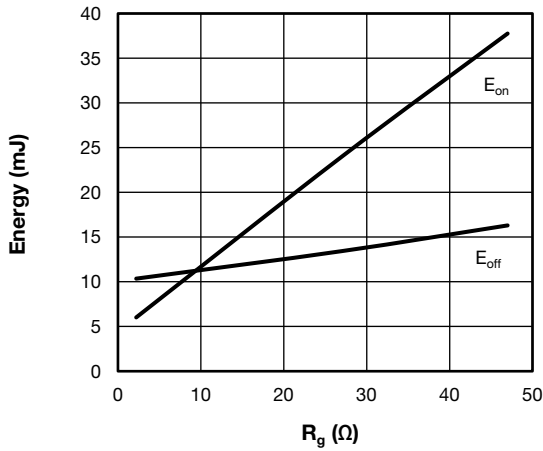


Fig. 11 - Typical IGBT Energy Losses vs.  $R_g$   
 $T_J = 125\text{ }^\circ\text{C}$ ,  $I_C = 100\text{ A}$ ,  $L = 500\text{ }\mu\text{H}$ ,  $V_{CC} = 720\text{ V}$ ,  $V_{GE} = 15\text{ V}$   
 Diode used: HFA16PB120

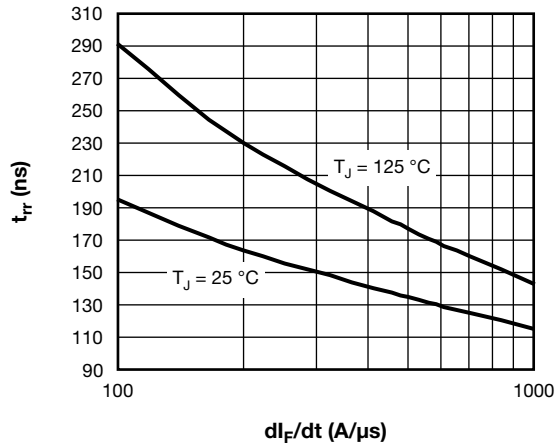


Fig. 13 - Typical Reverse Recovery Time vs.  $dI_F/dt$ , of Diode,  
 at  $I_F = 50\text{ A}$ ,  $V_R = 400\text{ V}$

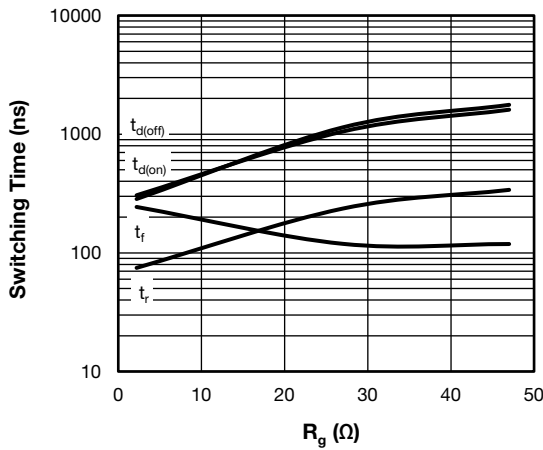


Fig. 12 - Typical IGBT Switching Time vs.  $R_g$   
 $T_J = 125\text{ }^\circ\text{C}$ ,  $L = 500\text{ }\mu\text{H}$ ,  $V_{CC} = 720\text{ V}$ ,  $I_C = 100\text{ A}$ ,  $V_{GE} = 15\text{ V}$   
 Diode used: HFA16PB120

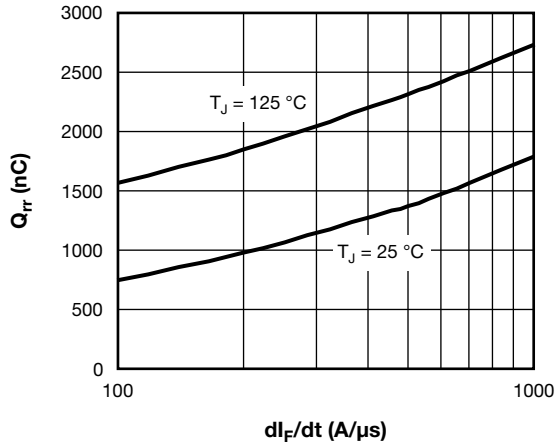


Fig. 14 - Typical Stored Charge vs.  $dI_F/dt$  of Diode,  
 at  $I_F = 50\text{ A}$ ,  $V_R = 400\text{ V}$

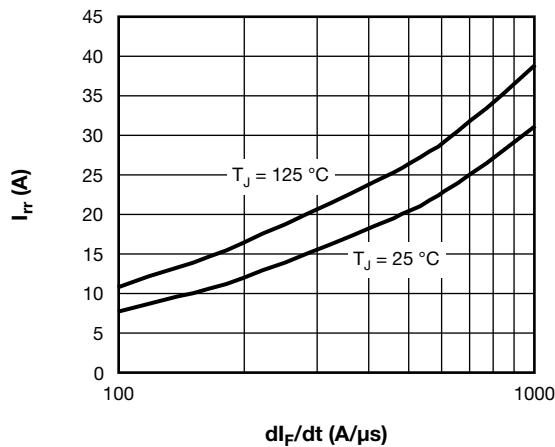


Fig. 15 - Typical Reverse Recovery Current vs.  $dI_F/dt$ , of Diode,  
 at  $I_F = 50\text{ A}$ ,  $V_R = 400\text{ V}$

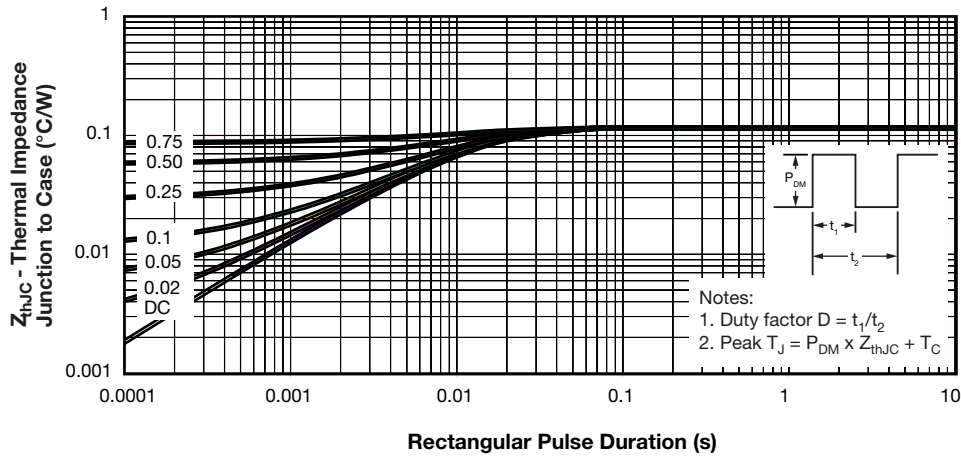


Fig. 16 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics (IGBT)

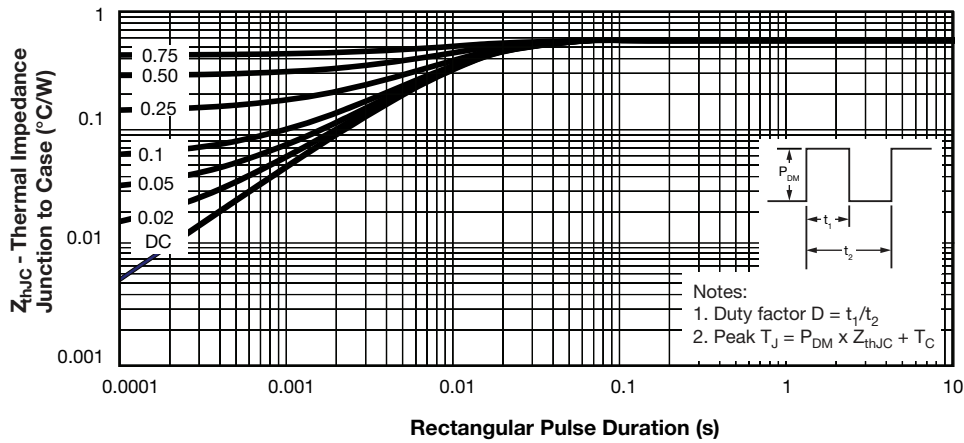


Fig. 17 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics (Diode)

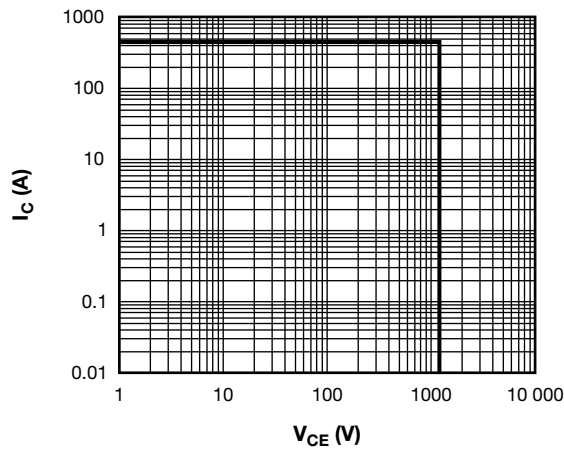
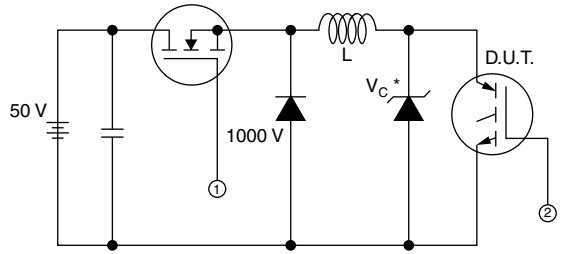


Fig. 18 - IGBT Reverse Bias SOA,  $T_J = 150\text{ }^\circ\text{C}$ ,  $V_{GE} = 15\text{ V}$



\* Driver same type as D.U.T.;  $V_C = 80\%$  of  $V_{ce(max)}$   
 \* Note: Due to the 50 V power supply, pulse width and inductor will increase to obtain  $I_d$

Fig. 19 - Clamped Inductive Load Test Circuit

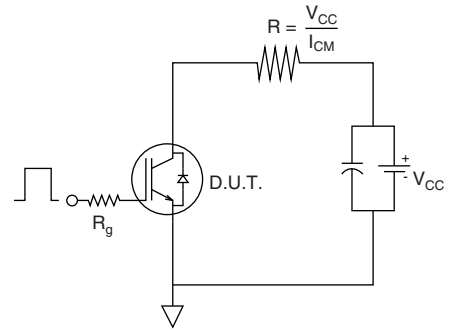


Fig. 19b - Pulsed Collector Current Test Circuit

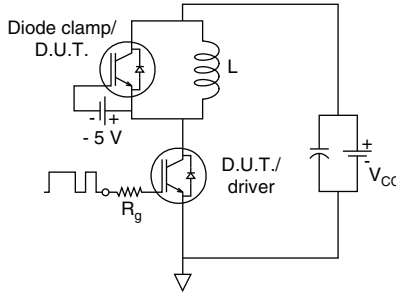


Fig. 20a - Switching Loss Test Circuit

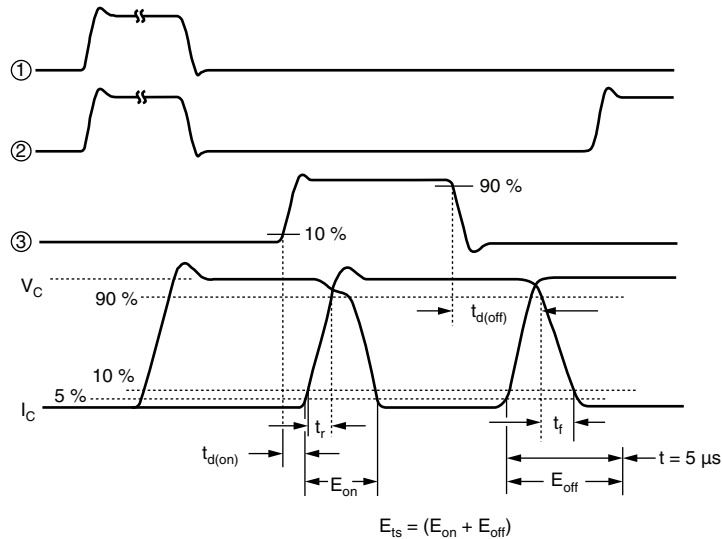


Fig. 20b - Switching Loss Waveforms Test Circuit



**ORDERING INFORMATION TABLE**

Device code	<b>VS-</b>	<b>G</b>	<b>T</b>	<b>175</b>	<b>D</b>	<b>A</b>	<b>120</b>	<b>U</b>
	①	②	③	④	⑤	⑥	⑦	⑧

- 1** - Vishay Semiconductors product
- 2** - Insulated Gate Bipolar Transistor (IGBT)
- 3** - Trench IGBT technology
- 4** - Current rating (175 = 175 A)
- 5** - Circuit configuration (D = Single switch with antiparallel diode)
- 6** - Package indicator (A = SOT-227)
- 7** - Voltage rating (120 = 1200 V)
- 8** - Speed/type (U = Ultrafast)

<b>CIRCUIT CONFIGURATION</b>		
<b>CIRCUIT</b>	<b>CIRCUIT CONFIGURATION CODE</b>	<b>CIRCUIT DRAWING</b>
Single switch diode	D	

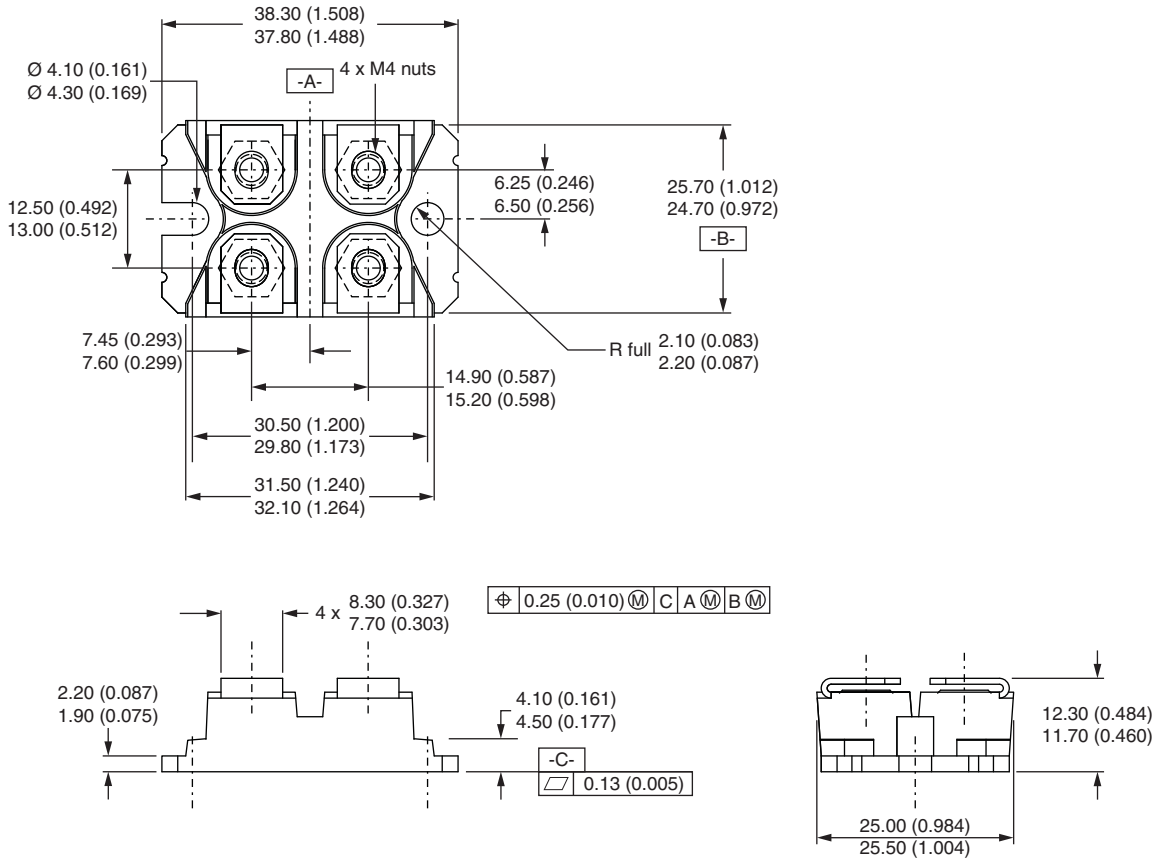
<b>LINKS TO RELATED DOCUMENTS</b>	
Dimensions	<a href="http://www.vishay.com/doc?95423">www.vishay.com/doc?95423</a>
Packaging information	<a href="http://www.vishay.com/doc?95425">www.vishay.com/doc?95425</a>





### SOT-227 Generation II

**DIMENSIONS** in millimeters (inches)



**Note**

- Controlling dimension: millimeter



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[FD401R17KF6C\\_B2](#) [FD-DF80R12W1H3\\_B52](#) [FF200R06YE3](#) [FF300R12KE4\\_E](#) [FF450R12ME4P](#) [FF600R12IP4V](#) [FP15R12W2T4](#)  
[FP20R06W1E3](#) [FP50R12KT3](#) [FP75R07N2E4\\_B11](#) [FS10R12YE3](#) [FS150R07PE4](#) [FS150R12PT4](#) [FS200R12KT4R](#) [FS20R06W1E3\\_B11](#)  
[FS50R07N2E4\\_B11](#) [FZ1000R33HE3](#) [FZ1800R17KF4](#) [DD250S65K3](#) [DF1000R17IE4](#) [DF1000R17IE4D\\_B2](#) [DF1400R12IP4D](#)  
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[FF650R17IE4D\\_B2](#) [FF900R12IP4D](#) [FF900R12IP4DV](#) [FP50R07N2E4\\_B11](#) [FS100R07PE4](#) [FS150R07N3E4\\_B11](#) [FS150R17N3E4](#)  
[FS150R17PE4](#)